

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

TPCF8301

Notebook PC Applications

Portable Equipment Applications

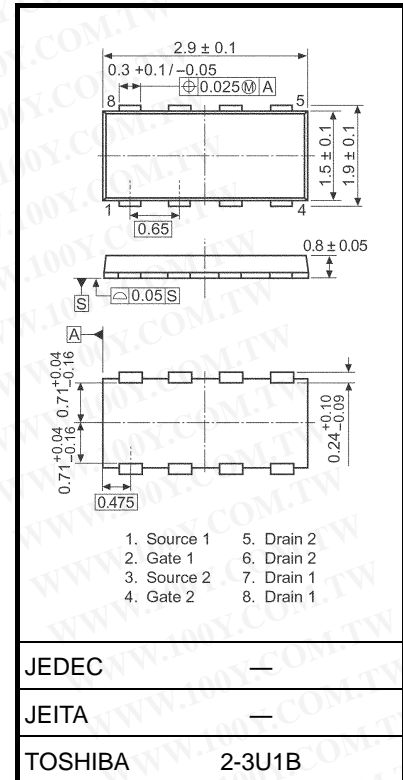
- Low drain-source ON resistance: $R_{DS(ON)} = 72\text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 4.7\text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = -10\text{ }\mu\text{A}$ (max) ($V_{DS} = -20\text{ V}$)
- Enhancement model: $V_{th} = -0.5\text{ to }-1.2\text{ V}$
($V_{DS} = -10\text{ V}$, $I_D = -200\text{ }\mu\text{A}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

| Characteristics | | Symbol | Rating | Unit |
|--|---|-----------|---------|------------------|
| Drain-source voltage | | V_{DSS} | -20 | V |
| Drain-gate voltage ($R_{GS} = 20\text{ k}\Omega$) | | V_{DGR} | -20 | V |
| Gate-source voltage | | V_{GSS} | ± 8 | V |
| Drain current | DC (Note 1) | I_D | -2.7 | A |
| | Pulse (Note 1) | I_{DP} | -10.8 | |
| Drain power dissipation ($t = 5\text{ s}$) (Note 2a) | Single-device operation (Note 3a) | $P_D(1)$ | 1.35 | W |
| | Single-device value at dual operation (Note 3b) | $P_D(2)$ | 1.12 | |
| Drain power dissipation ($t = 5\text{ s}$) (Note 2b) | Single-device operation (Note 3a) | $P_D(1)$ | 0.53 | |
| | Single-device value at dual operation (Note 3b) | $P_D(2)$ | 0.33 | |
| Single pulse avalanche energy (Note 4) | | E_{AS} | 1.2 | mJ |
| Avalanche current | | I_{AR} | -1.35 | A |
| Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5) | | E_{AR} | 0.11 | mJ |
| Channel temperature | | T_{ch} | 150 | $^\circ\text{C}$ |
| Storage temperature range | | T_{stg} | -55~150 | $^\circ\text{C}$ |

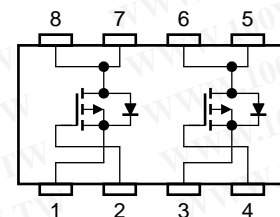
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Unit: mm



Weight: 0.011 g (typ.)

Circuit Configuration



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Thermal Characteristics

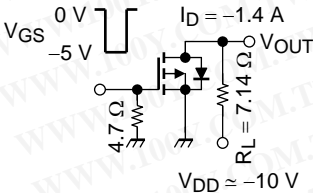
| Characteristics | | Symbol | Max | Unit |
|--|---|----------------------------|-------|------|
| Thermal resistance, channel to ambient (t = 5 s) (Note 2a) | Single-device operation (Note 3a) | R _{th} (ch-a) (1) | 92.6 | °C/W |
| | Single-device value at dual operation (Note 3b) | R _{th} (ch-a) (2) | 111.6 | |
| Thermal resistance, channel to ambient (t = 5 s) (Note 2b) | Single-device operation (Note 3a) | R _{th} (ch-a) (1) | 235.8 | °C/W |
| | Single-device value at dual operation (Note 3b) | R _{th} (ch-a) (2) | 378.8 | |

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Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6): See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

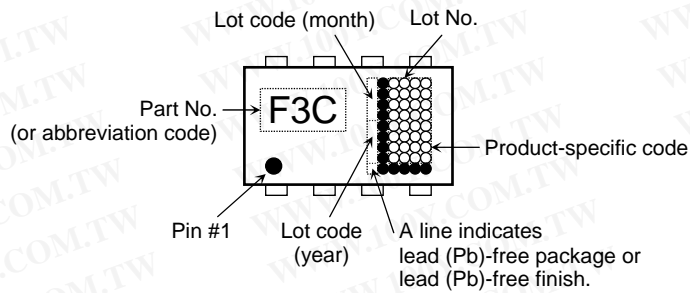
Electrical Characteristics (T_a = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|---------------|----------------------|--|------|------|------|------|
| Gate leakage current | | I _{GSS} | V _{GS} = ±8 V, V _{DS} = 0 V | — | — | ±10 | μA |
| Drain cut-off current | | I _{DSS} | V _{DS} = -20 V, V _{GS} = 0 V | — | — | -10 | μA |
| Drain-source breakdown voltage | | V (BR) DSS | I _D = -10 mA, V _{GS} = 0 V | -20 | — | — | V |
| | | V (BR) DSX | I _D = -10 mA, V _{GS} = 8 V | -12 | — | — | |
| Gate threshold voltage | | V _{th} | V _{DS} = -10 V, I _D = -200 μA | -0.5 | — | -1.2 | V |
| Drain-source ON resistance | | R _{DS} (ON) | V _{GS} = -1.8 V, I _D = -0.7 A | — | 215 | 300 | mΩ |
| | | R _{DS} (ON) | V _{GS} = -2.5 V, I _D = -1.4 A | — | 110 | 160 | |
| | | R _{DS} (ON) | V _{GS} = -4.5 V, I _D = -1.4 A | — | 72 | 110 | |
| Forward transfer admittance | | Y _{fs} | V _{DS} = -10 V, I _D = -1.4 A | 2.4 | 4.7 | — | S |
| Input capacitance | | C _{iss} | V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz | — | 470 | — | pF |
| Reverse transfer capacitance | | C _{rss} | | — | 70 | — | |
| Output capacitance | | C _{oss} | | — | 80 | — | |
| Switching time | Rise time | t _r |  V _{DD} ≈ -10 V Duty ≤ 1%, t _w = 10 μs | — | 5 | — | ns |
| | Turn-on time | t _{on} | | — | 9 | — | |
| | Fall time | t _f | | — | 8 | — | |
| | Turn-off time | t _{off} | | — | 26 | — | |
| Total gate charge (gate-source plus gate-drain) | | Q _g | V _{DD} ≈ -16 V, V _{GS} = -5 V, I _D = -2.7 A | — | 6 | — | nC |
| Gate-source charge | | Q _{gs} | | — | 4 | — | |
| Gate-drain (“miller”) charge | | Q _{gd} | | — | 2 | — | |

Source-Drain Ratings and Characteristics (T_a = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-------------------------|----------------|------------------|---|-----|------|-------|------|
| Drain reverse current | Pulse (Note 1) | I _{DRP} | — | — | — | -10.8 | A |
| Forward voltage (diode) | | V _{DSF} | I _{DR} = -2.7 A, V _{GS} = 0 V | — | — | 1.2 | V |

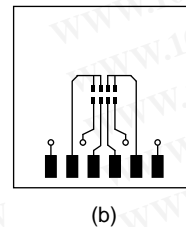
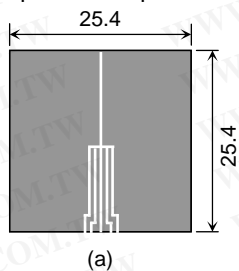
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)

Note 3: a) The power dissipation and thermal resistance values are shown for a single device



(During single-device operation, power is only applied to one device.).

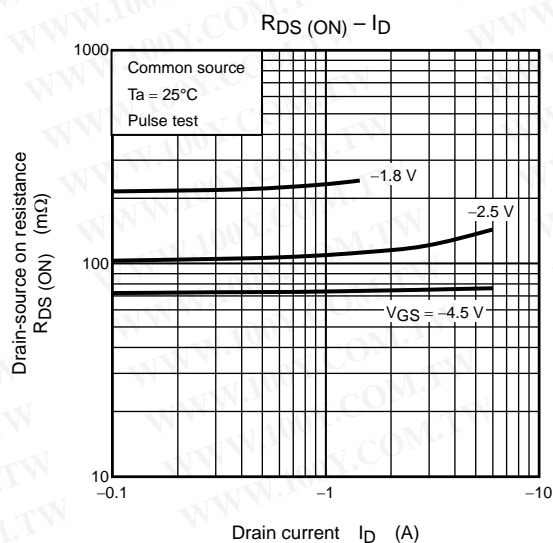
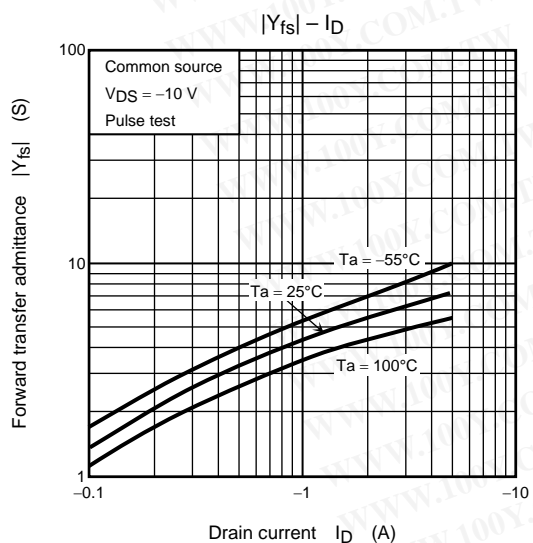
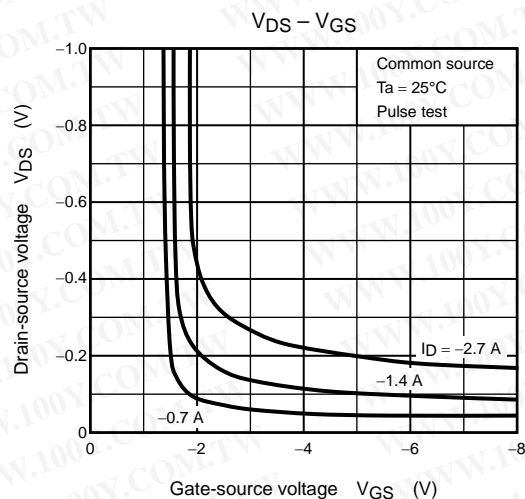
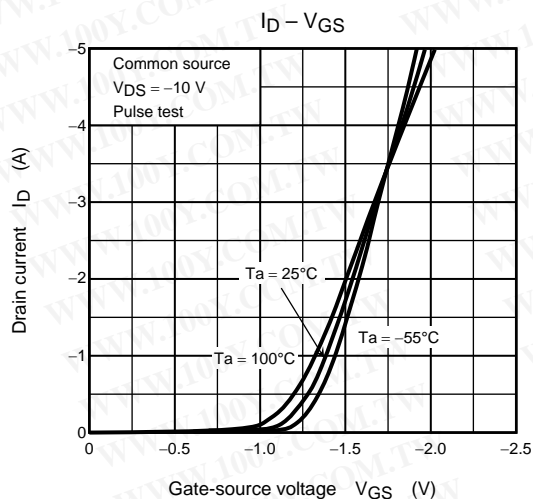
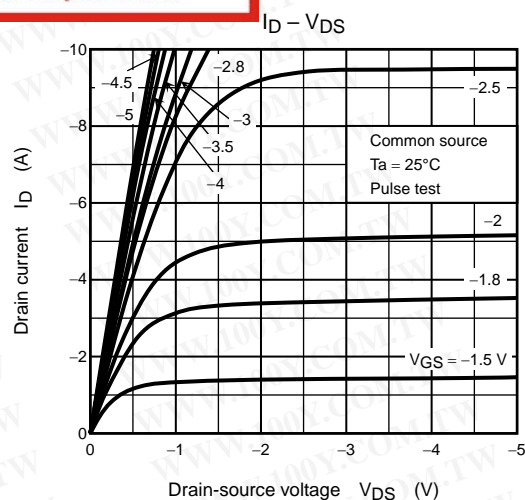
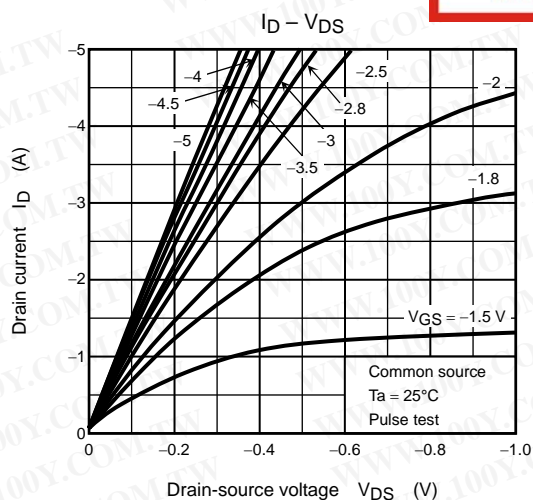
b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

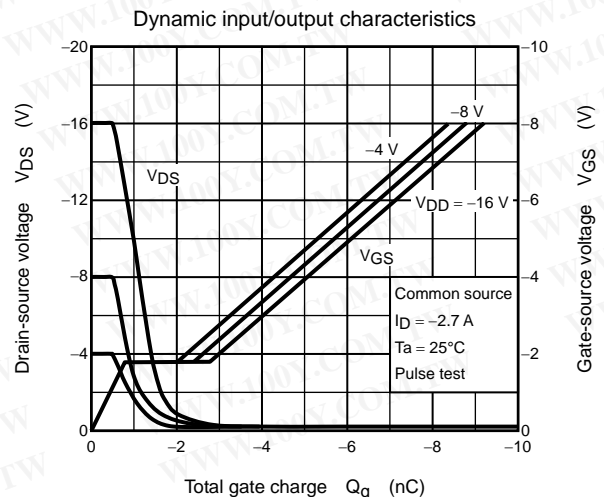
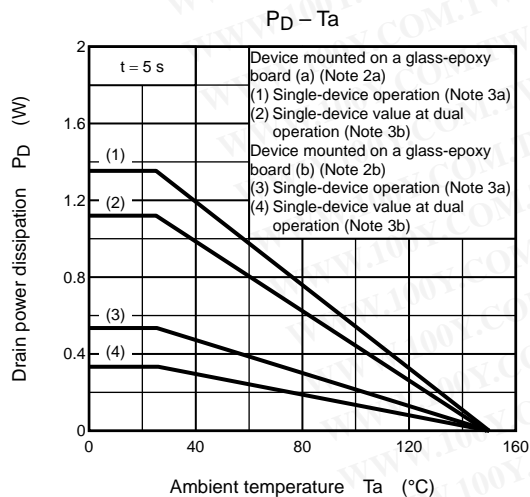
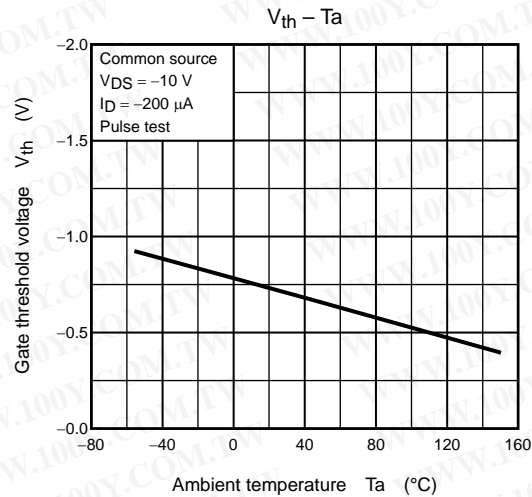
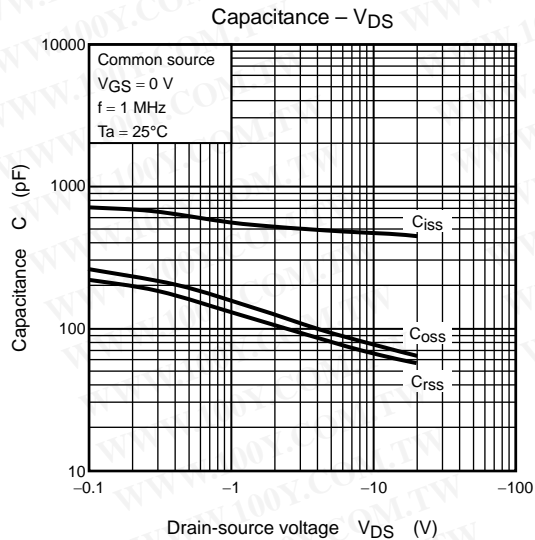
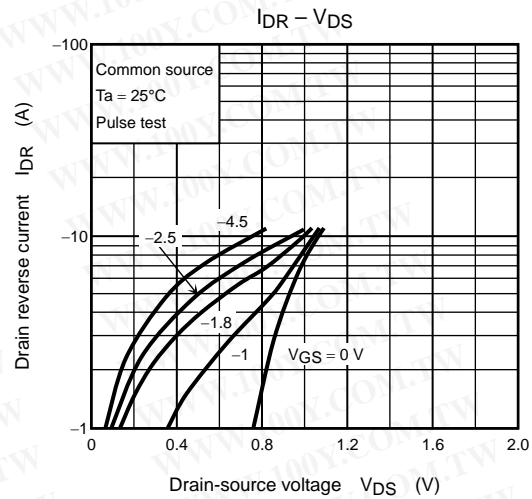
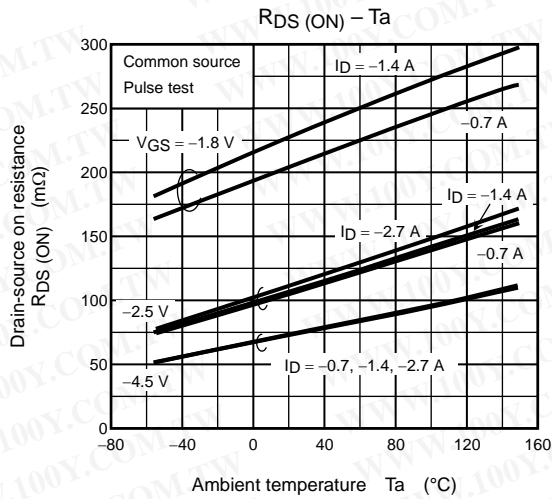
Note 4: $V_{DD} = -16\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5\text{ mH}$, $R_G = 25\ \Omega$, $I_{AR} = -1.35\text{ A}$

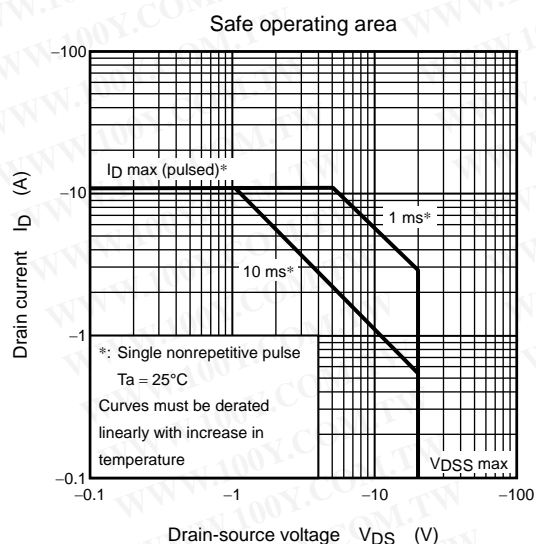
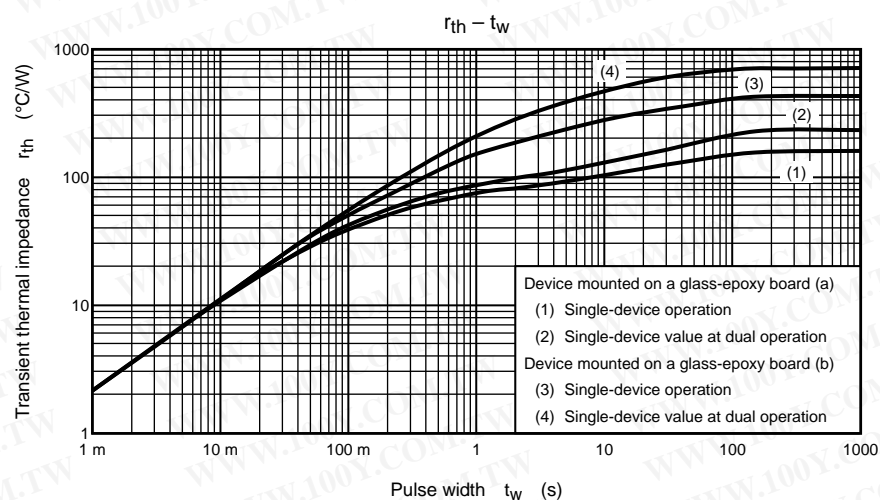
Note 5: Repetitive rating: Pulse width limited by maximum channel temperature.

Note 6: A dot on the lower left of the marking indicates Pin 1

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